

L Number	Hits	Search Text	DB	Time stamp
1	2464	(438/128,108,129).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:00
2	0	("1 and (aperture or via)").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:01
3	504	((438/128,108,129).CCLS.) and (aperture or via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:01
4	239	((438/128,108,129).CCLS.) and (aperture or via)) and (diameter or width)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:02
5	65	((438/128,108,129).CCLS.) and (aperture or via)) and (diameter or width)) and ((via or aperture) same (width or diameter))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:02
6	14	((438/128,108,129).CCLS.) and (aperture or via)) and (diameter or width)) and ((via or aperture) same (width or diameter))) and ((via or aperture) near3 (width or diameter))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:02

438/106

257/783

438/108

438/614

L Number	Hits	Search Text	DB	Time stamp
1	2	("6,265,782").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:49
2	2308	(438/118,119,128).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:49
3	288	((438/118,119,128).CCLS.) and (adhesive and (temperature and pressure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:51
4	81	((((438/118,119,128).CCLS.) and (adhesive and (temperature and pressure))) and (adhesive near3 substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:52
5	51	(((((438/118,119,128).CCLS.) and (adhesive and (temperature and pressure))) and (adhesive near3 substrate)) and (via or (opening or throughADJhole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:53
6	58	(((((438/118,119,128).CCLS.) and (adhesive and (temperature and pressure))) and (adhesive near3 substrate)) and (via or (opening or throughADJhole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 13:54

L Number	Hits	Search Text	DB	Time stamp
1	3	832160.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 06:52
2	3	("5846875").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 06:59
3	2511	"bump electrodes" or ubm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 07:00
4	181	("bump electrodes" or ubm) and ((tin and lead) or (tin and silver))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 07:01
5	58	((("bump electrodes" or ubm) and ((tin and lead) or (tin and silver))) and (csp or bga)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 07:01